

an engaging roller defined within the enclosure, the engaging roller configured to engage the substrate to be processed, the engaging roller and the pair of drive rollers configured to engage the substrate to be processed such that the substrate to be processed creates an angle with the horizontal plane that is substantially equivalent to the process angle; and

a plurality of gas blow nozzles defined within an inner wall of the enclosure, at least one gas blow nozzle being configured to dispense a first gas onto each of the drive rollers and the engaging roller.

Claim 30 (previously added): A spin, rinse, and dry module comprising:

an enclosure having an outer wall, the outerwall being configured to include a window therein, the window being defined within the outerwall so as to create a process angle with a horizontal plane;

a pair of drive rollers defined within the enclosure, the drive rollers being configured to spin a substrate to be processed while engaging the substrate to be processed;

an engaging roller defined within the enclosure, the engaging roller configured to engage the substrate to be processed, the engaging roller and the pair of drive rollers configured to engage the substrate to be processed such that the substrate to be processed creates an angle with the horizontal plane that is substantially equivalent to the process angle; and

a plurality of holes defined within an inner wall of the enclosure so as to introduce a second gas into the enclosure, the second gas being configured to substantially evenly dry a top surface and a bottom surface of the substrate to be processed.

Claim 31 (currently amended):        A wafer preparation module, comprising:

an enclosure containing wafer engaging rollers, the wafer engaging rollers being suspended at an angle, the wafer engaging rollers designed to spin a wafer at an angle during preparation, the enclosure further having an inner wall containing a plurality of holes defined therein, the plurality of holes being configured to introduce a gas into the enclosure, the gas being configured to substantially evenly dry a top surface and a bottom surface of the wafer to be processed.